Method and apparatus for thermally processing plastic discs, in particular mould wafers

ABSTRACT

The present invention provides a method and apparatus for thermally processing plastic discs, in particular mould wafers. The method comprises the following steps: clamping a mould wafer (15) at a first temperature (T1) on a first clamping device (5; 50), the first temperature (T1) being below the hardening temperature (T_H) of the plastic of the mould wafer (15); heating the mould wafer (15) clamped on the first clamping device (5; 50) to a second temperature (T2), which is higher than the first temperature (T1) and is above the hardening temperature (T_H); ending the clamping on the first clamping device (5; 50) and transporting the mould wafer (15) heated to the second temperature (T2) from the first clamping device (5; 50) to a second clamping device (9; 90) substantially contactlessly; clamping the heated mould wafer (15) on the second clamping device (9; 90); cooling the mould wafer (15) clamped on the second clamping device (9; 90) down to a third temperature (T4), which is lower than the second temperature (T2) and is below the hardening temperature (T_H); and ending the clamping on the second clamping device (9; 90).

Fig. 1a